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**Method for Fabrication of a Contact Structure****Abstract**

- 5 A method for producing a contact structure on a structured surface comprising producing a first conductive layer on the structured surface, wherein the first conductive layer comprising tungsten. A conductive seed layer is produced on the first conductive layer, the contact structure being
- 10 produced by electroplating on the seed layer. The first conductive layer serves as an etch stop for selectively removing substrate material from the backside.